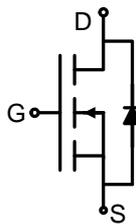
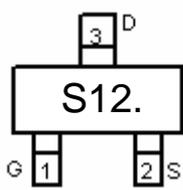


## N-Channel Enhancement Mode Power MOSFET

<p><b>Description</b></p> <p>The FTK2312A uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.</p> <p><b>General Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS} = 20V, I_D = 6A</math></li> <li style="padding-left: 20px;"><math>R_{DS(ON)} &lt; 28m\Omega @ V_{GS}=2.5V</math></li> <li style="padding-left: 20px;"><math>R_{DS(ON)} &lt; 22m\Omega @ V_{GS}=4.5V</math></li> <li>● High power and current handing capability</li> <li>● Lead free product is acquired</li> <li>● Surface mount package</li> <li>● AEC-Q101 qualified</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Battery protection</li> <li>● Load switch</li> <li>● Power management</li> </ul>	<div style="text-align: center;">  <p>Schematic diagram</p>  <p>Marking and pin assignment</p>  <p>SOT-23 top view</p> </div>
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### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
S12.	FTK2312A	SOT-23	Ø180mm	8 mm	3000 units

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	V
Drain Current-Continuous	$I_D$	6	A
Drain Current-Pulsed <sup>(Note 1)</sup>	$I_{DM}$	15	A
Maximum Power Dissipation	$P_D$	1.25	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	100	$^\circ C/W$
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### Electrical Characteristics ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	20	22	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=20V, V_{GS}=0V$	-	-	1	$\mu A$



# FTK2312A

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.65	1.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=2.5V, I_D=4.5 A$	-	20	28	m $\Omega$
		$V_{GS}=4.5V, I_D=5A$	-	17	22	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=15V, I_D=5A$	25	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note4)</sup>						
Input Capacitance	$C_{ISS}$	$V_{DS}=10V, V_{GS}=0V,$ $F=1.0MHz$	-	780	-	PF
Output Capacitance	$C_{OSS}$		-	140	-	PF
Reverse Transfer Capacitance	$C_{RSS}$		-	80	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, I_D=1A$ $V_{GS}=4.5V, R_{GEN}=6\Omega$	-	9	-	nS
Turn-on Rise Time	$t_r$		-	30	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	35	-	nS
Turn-Off Fall Time	$t_f$		-	10	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=10V, I_D=5A, V_{GS}=4.5V$	-	11	-	nC
Gate-Source Charge	$Q_{gs}$		-	2.3	-	nC
Gate-Drain Charge	$Q_{gd}$		-	2.9	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1A$	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_S$		-	-	5	A

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

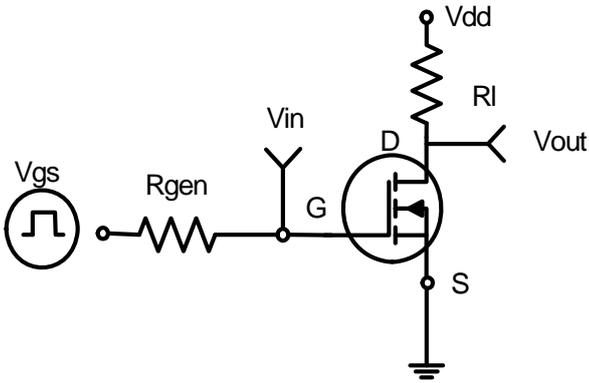


Figure 1: Switching Test Circuit

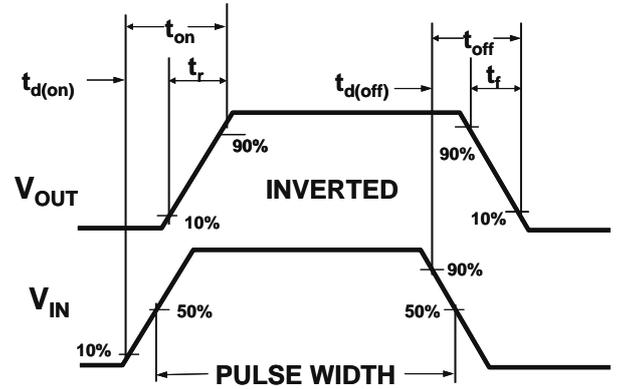
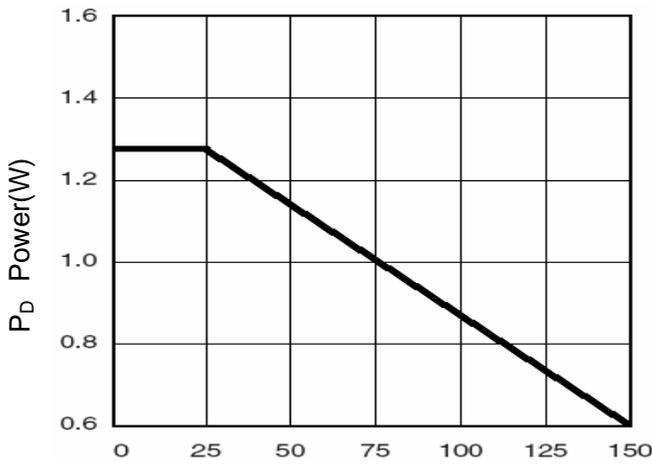
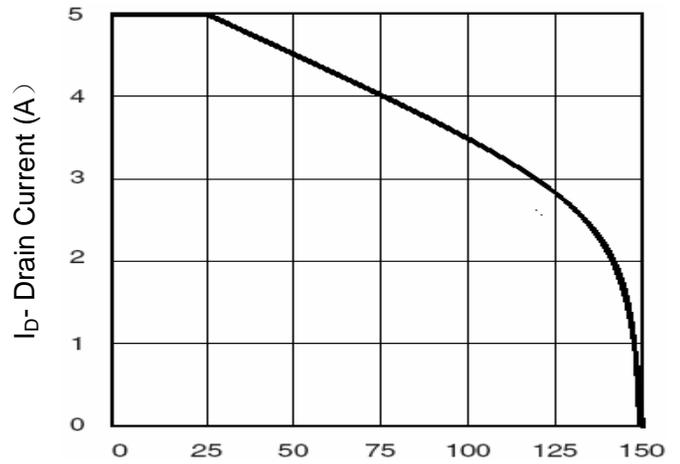


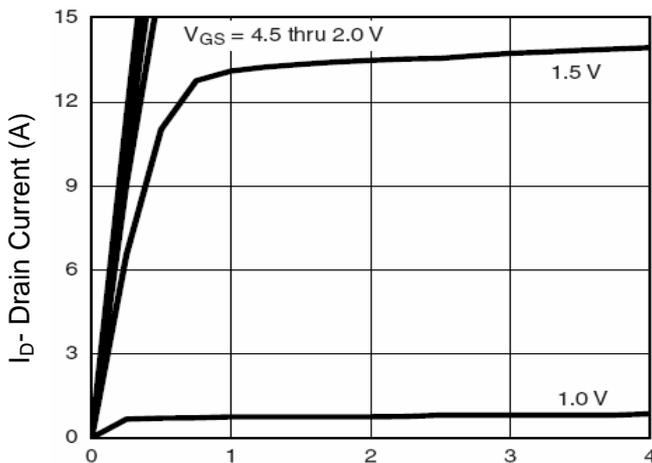
Figure 2: Switching Waveforms



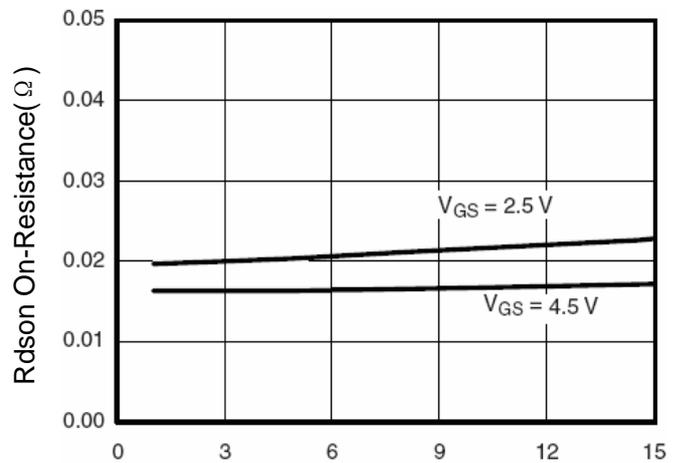
T<sub>J</sub>-Junction Temperature (°C)  
Figure 3 Power Dissipation



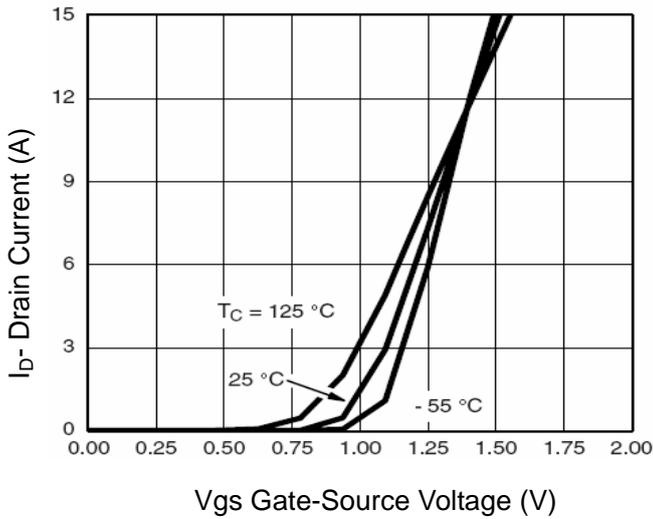
T<sub>J</sub>-Junction Temperature (°C)  
Figure 4 Drain Current



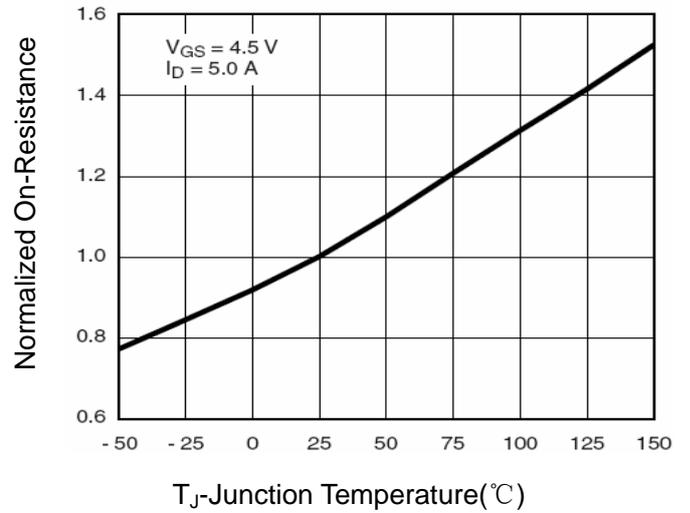
V<sub>ds</sub> Drain-Source Voltage (V)  
Figure 5 Output Characteristics



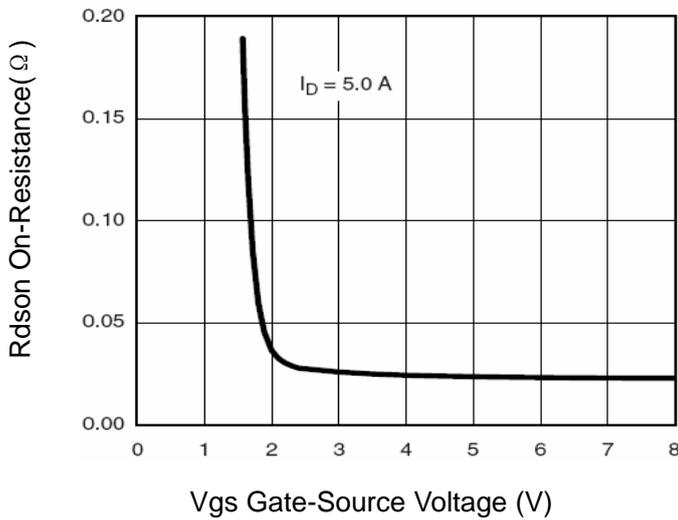
I<sub>D</sub>- Drain Current (A)  
Figure 6 Drain-Source On-Resistance



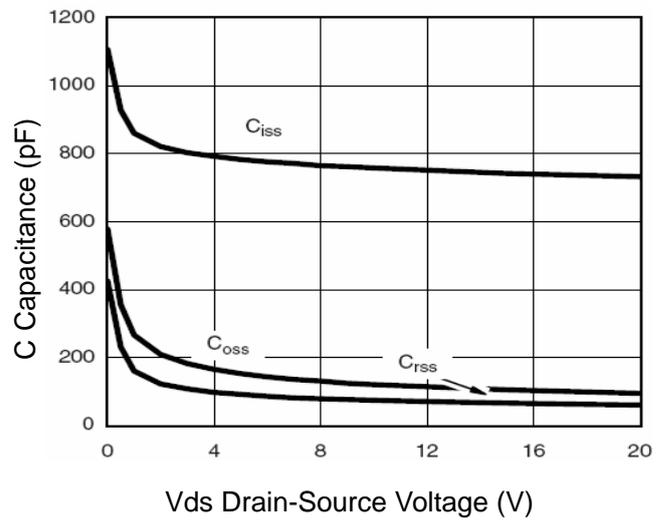
**Figure 7 Transfer Characteristics**



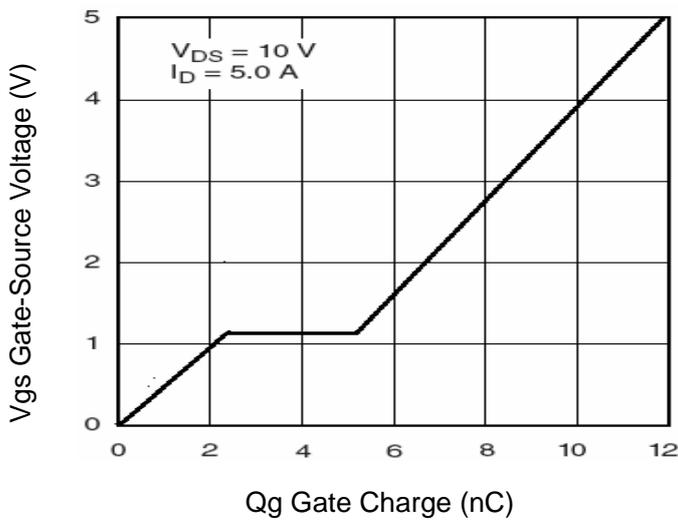
**Figure 8 Drain-Source On-Resistance**



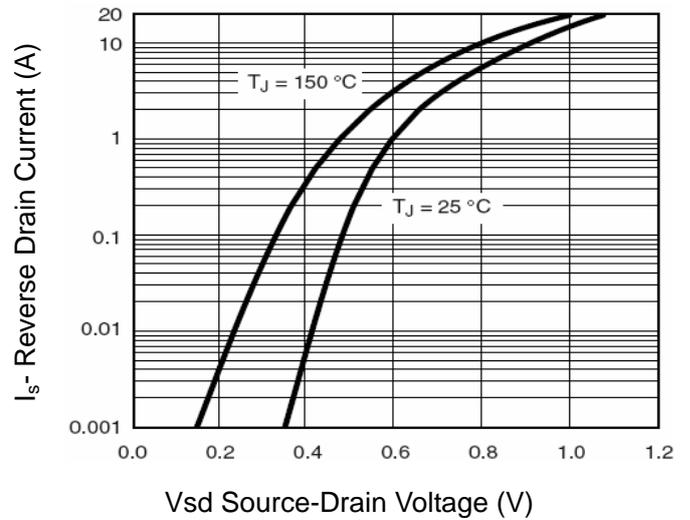
**Figure 9 Rdson vs Vgs**



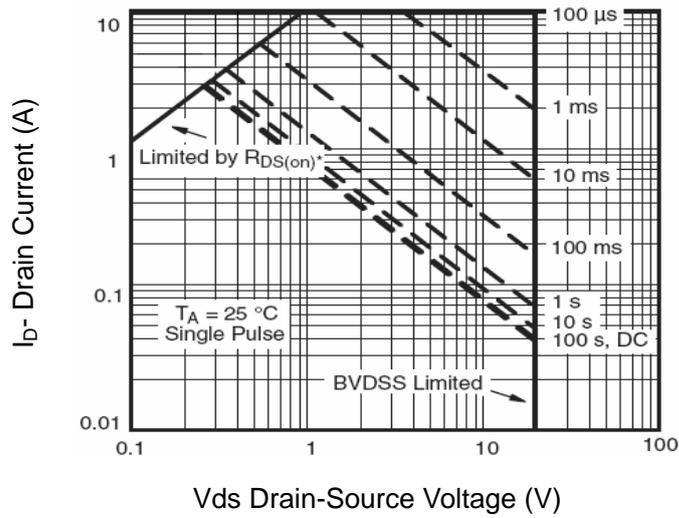
**Figure 10 Capacitance vs Vds**



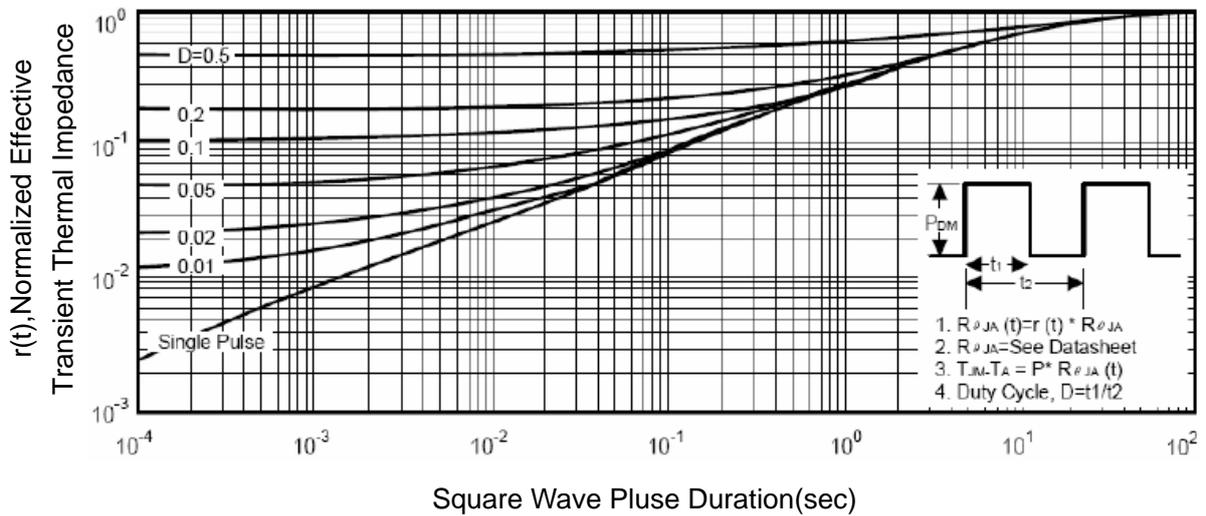
**Figure 11 Gate Charge**



**Figure 12 Source- Drain Diode Forward**

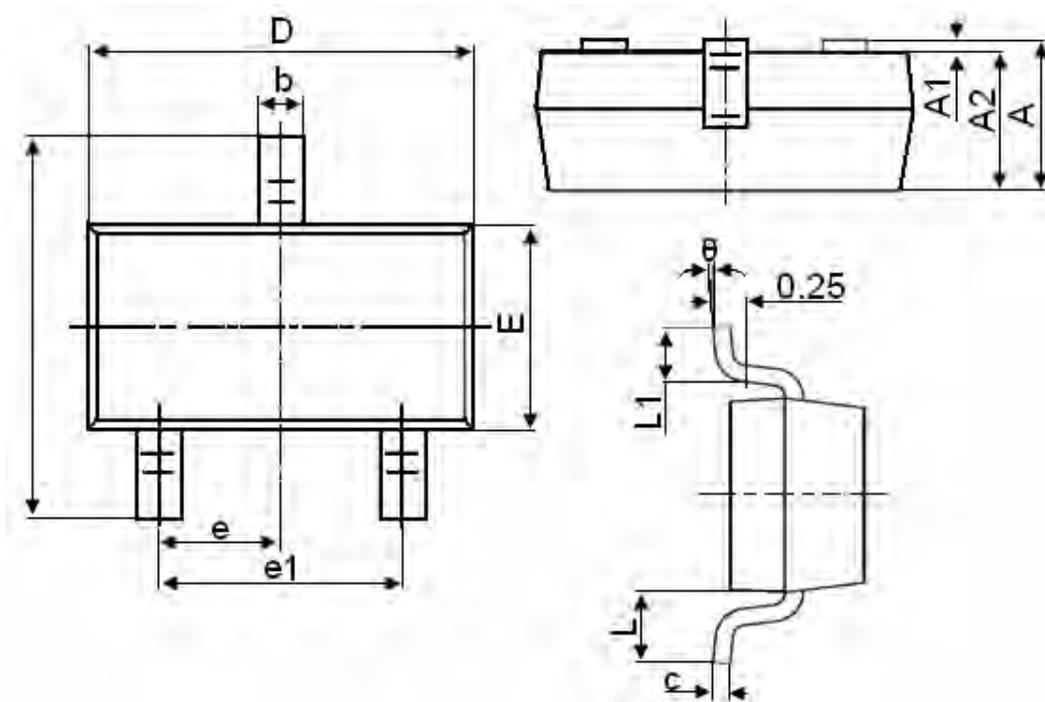


**Figure 13 Safe Operation Area**



**Figure 14 Normalized Maximum Transient Thermal Impedance**

## SOT-23 Package Information



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

### Notes

1. All dimensions are in millimeters.
2. Tolerance  $\pm 0.10\text{mm}$  (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.